



# 100% Material Declaration Data Sheet VOG8

PK179 (v1.3) February 20, 2007

Material Declaration Data Sheet

**Average Weight: 0.536 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.012692</b>	<b>2.37%</b>
	Silicon	7440-21-3	99.00		0.012616	
	Al	7429-90-5	1.00		0.000076	
<b>Die Attach Material</b>					<b>0.002756</b>	<b>0.52%</b>
	Epoxy resin (EP)	29690-82-2	25.00		0.00069	
	Silver	7440-22-4	75.00		0.002066	
<b>Encapsulation</b>					<b>0.34461387</b>	<b>64.35%</b>
	Resin	29690-82-2	26.00		0.09129027	
	SiO2 Filler	60676-86-0	74.00		0.2533236	
<b>Leadframe</b>					<b>0.16785816</b>	<b>31.35%</b>
	Copper	7440-50-8	58.00		0.167656	
	Iron	7439-89-6	42.00		0.00020216	
<b>Bond Wire</b>					<b>0.0007</b>	<b>0.13%</b>
	Gold	7440-57-5	100.00		0.0007	
<b>Ext. Plating</b>					<b>0.00688</b>	<b>1.28%</b>
	Tin	7440-31-5	100.00		0.00688	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
5/16/06	1.0	Initial release.
6/13/06	1.1	100% Material Declaration.
9/25/06	1.2	Updated component descriptions.
2/20/07	1.3	Updated component descriptions and weights.